

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **06244238 A**

(43) Date of publication of application: **02.09.94**

(51) Int. Cl.

H01L 21/60

(21) Application number: **05027709**

(22) Date of filing: **17.02.93**

(71) Applicant: **MATSUSHITA ELECTRIC IND CO LTD**

(72) Inventor: **NAGAO KOICHI
FUJIMOTO HIROAKI**

(54) **PACKAGING METHOD OF MULTICHIP MODULE**

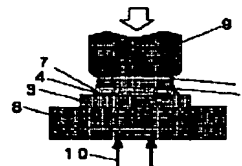
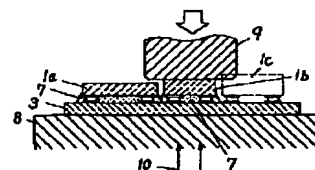
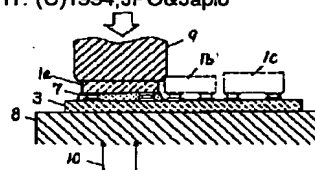
of the packaging device to be realized.

(57) Abstract:

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PURPOSE: To provide the packaging method in the microbump bonding mode capable of continuously packaging multiple semiconductor elements in different sizes and shapes using the same pressurizing jig.

CONSTITUTION: The packaging method of multichip module is characterized by the connection of multiple semiconductor elements 1a-1c to a wiring board 3 in the order from the thinnest one among the semiconductor elements using the same pressurizing jig by repeating the two steps as follows i.e., the first step of coating the gaps between the semiconductor elements 1a-1c and a wiring board 3 with an insulating resin 7 to make alignment and the second step of curing the insulating region 7 in the state of pressurized semiconductor element 1 and after releasing the pressurization, electrically connecting the electrode 2 of the semiconductor element 1 to the electrode 4 of the wiring board 3. Through these procedures, the packaging device can be made simple and cheaper as well as making the replacement of the pressurizing jig due to the model change needless thereby enabling the tact improvement



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